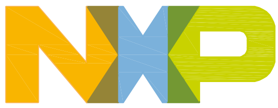

TOP VIEW

A1 INDEX; 33; B; 14.7 / 14.5; C; 6.6 MAX; 7.725 MAX; 2X 8.65 MIN; 33; 12.1 / 11.9; 4X CAP ZONES 5 6; 4X 0.2; 2X 10.7 MIN; 2X 7.895 MAX; 4X 14 MAX; 2X 9.05 MAX

BOTTOM VIEW

0.5; 31X 1; A1 CORNER; 1023X ø0.65 / 0.55 3; ø0.4 Ⓜ A B C; ø0.2 Ⓜ A

SIDE VIEW

1023X 0.2 A; // 0.25 A; A SEATING PLANE 4; 0.9 / 0.82; 4X 0.6 MAX; 0.75 / 0.55; 1.32 / 1.1; 2.97 MAX

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 1023 I/O, FC CBGA, 33 X 33 PKG, 1 MM PITCH, HIGH PB SPHERES	DOCUMENT NO: 98ARE10634D REV: F
	STANDARD: NON-JEDEC
	SOT1601-2 17 DEC 2015

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSE METAL CAPACITOR PADS ON PACKAGE TOP.

7. ALL DIMENSIONS SYMMETRICAL ABOUT CENTERLINES UNLESS OTHERWISE SPECIFIED.

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